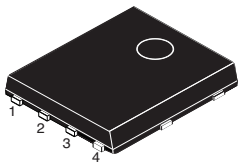
STL80N75F6

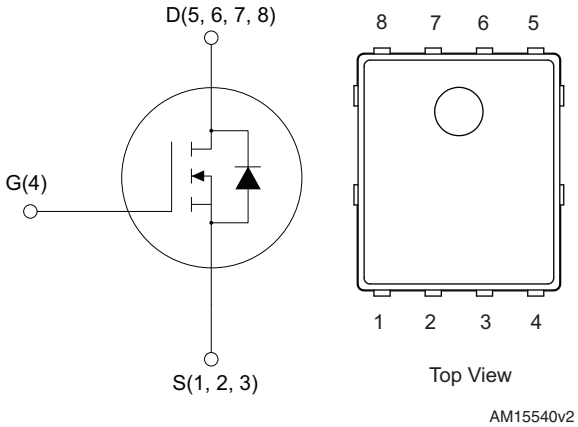
N-channel 75 V, 4.5 mΩ typ., 18 A STripFET™ DeepGATE™ VI Power MOSFET in PowerFLAT™ 5x6 package

Datasheet - production data



PowerFLAT™ 5x6

Figure 1. Internal schematic diagram



Features

Order code	V_{DS}	$R_{DS(on)}$ max	I_D
STL80N75F6	75 V	5.5 mΩ	18 A

- Low gate charge
- Very low on-resistance
- High avalanche ruggedness

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using the 6th generation of STripFET™ DeepGATE™ technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest $R_{DS(on)}$ in all packages.

Table 1. Device summary

Order code	Marking	Package	Packaging
STL80N75F6	80N75F6	PowerFLAT™ 5x6	Tape and reel

Contents

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	75	V
V_{GS}	Gate-source voltage	± 20	V
I_D (1)	Drain current (continuous) at T_C = 25 °C	80	A
I_D (2)	Drain current (continuous) at T_{pcb} = 25 °C	18	A
I_D (2)	Drain current (continuous) at T_{pcb}=100 °C	11	A
I_{DM} (2),(3)	Drain current (pulsed)	72	A
P_{TOT} (1)	Total dissipation at T_C = 25 °C	80	W
P_{TOT} (2)	Total dissipation at T_{pcb} = 25 °C	4	W
T_{stg}	Storage temperature	- 55 to 175	°C
T_j	Operating junction temperature		

1. The value is rated according to $R_{thj\text{-}c}$
2. The value is rated according to $R_{thj\text{-}pcb}$
3. Pulse width limited by safe operating area

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb max	31.3	°C/W
$R_{thj\text{-}case}$	Thermal resistance junction-case max.	1.56	°C/W

1. When mounted on FR-4 board of 1 inch², 2 oz Cu, t < 10 sec

Table 4. Avalanche characteristics

Symbol	Parameter	Max value	Unit
I_{AS}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_j max)	18	A
E_{AS}	Single pulse avalanche energy (starting T_j = 25 °C, I_D = I_{AS}, V_{DD} = 50 V)	730	mJ

2 Electrical characteristics

(T_J = 25 °C unless otherwise specified)

Table 5. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS}= 0	75			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = 75 V, V_{DS} = 75 V, T_C = 125 °C			1 10	μA μA
I_{GSS}	Gate body leakage current (V_{DS} = 0)	V_{GS} = ±20 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS}= V_{GS}, I_D = 250 μA	2		4	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS}= 10 V, I_D= 9 A		4.5	5.5	µΩ

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} =25 V, f = 1 MHz, V_{GS} = 0	-	6100	-	pF
C_{oss}	Output capacitance		-	530	-	pF
C_{rss}	Reverse transfer capacitance		-	185	-	pF
Q_g	Total gate charge	V_{DD} = 37.5 V, I_D = 18 A V_{GS} =10 V (see *Figure 14*)	-	78	-	nC
Q_{gs}	Gate-source charge		-	24	-	nC
Q_{gd}	Gate-drain charge		-	15	-	nC
R_g	Gate input resistance	f=1 MHz Gate DC Bias=0 test signal level=20 mV open drain	-	1.47	-	Ω

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD}= 37.5 V, I_D= 9 A, R_G=4.7 Ω, V_{GS}=10 V (see *Figure 13*)	-	28	-	ns
t_r	Rise time		-	17	-	ns
$t_{d(off)}$	Turn-off delay time		-	66	-	ns
t_f	Fall time		-	12	-	ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
I_{SD}	Source-drain current		-		18	A
I_{SDM}(1)	Source-drain current (pulsed)		-		72	A
V_{SD}(2)	Forward on voltage	I_{SD} = 18 A, V_{GS} = 0	-		1.5	V
t_{rr}	Reverse recovery time	I_{SD} = 18 A, di/dt = 100 A/µs, V_{DD}= 60 V, T_J = 150 °C (see *Figure 15*)	-	48		ns
Q_{rr}	Reverse recovery charge		-	96		nC
I_{RRM}	Reverse recovery current		-	4		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300 µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

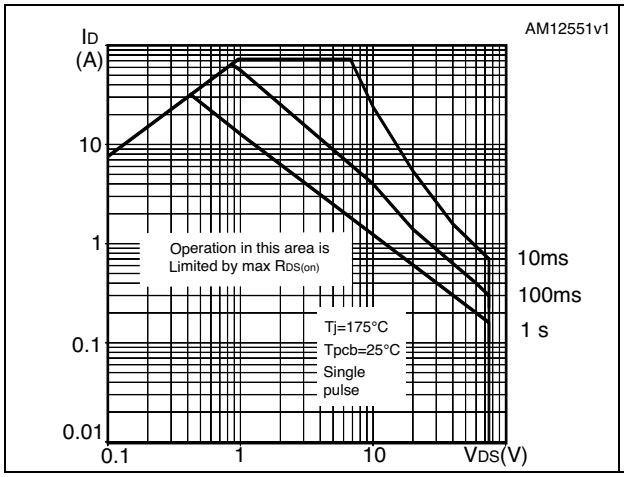


Figure 3. Thermal impedance

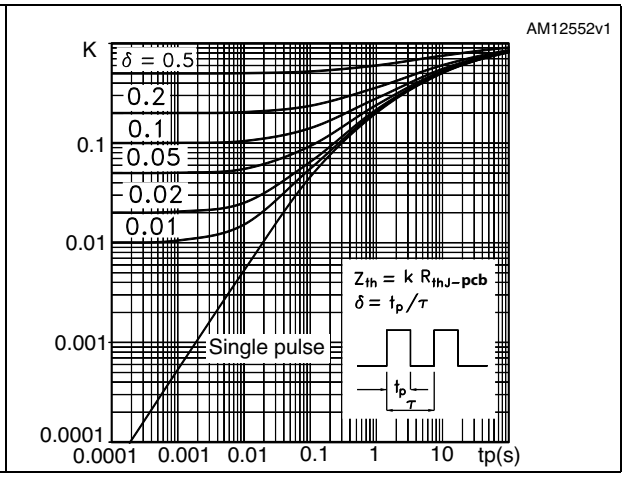


Figure 4. Output characteristics

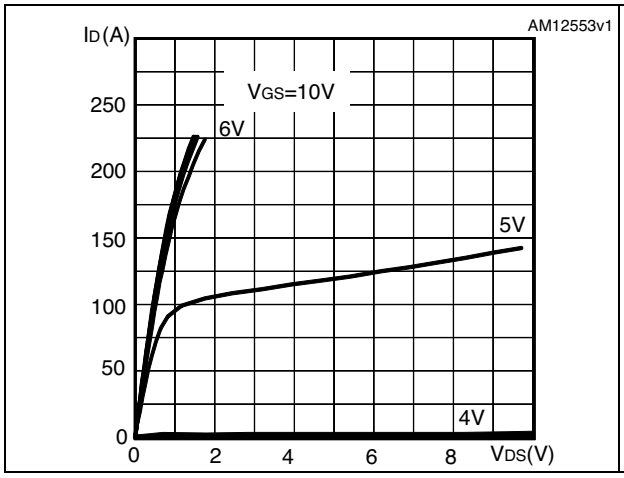


Figure 5. Transfer characteristics

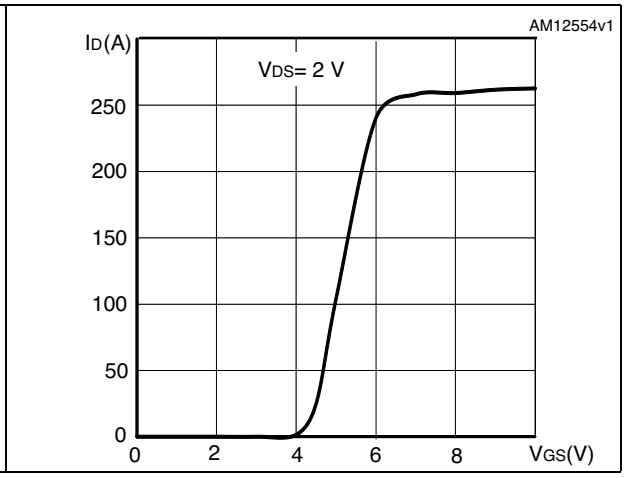


Figure 6. Gate charge vs gate-source voltage

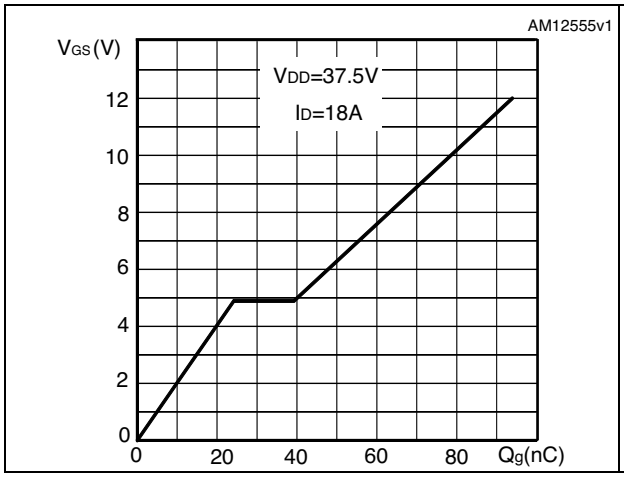


Figure 7. Static drain-source on-resistance

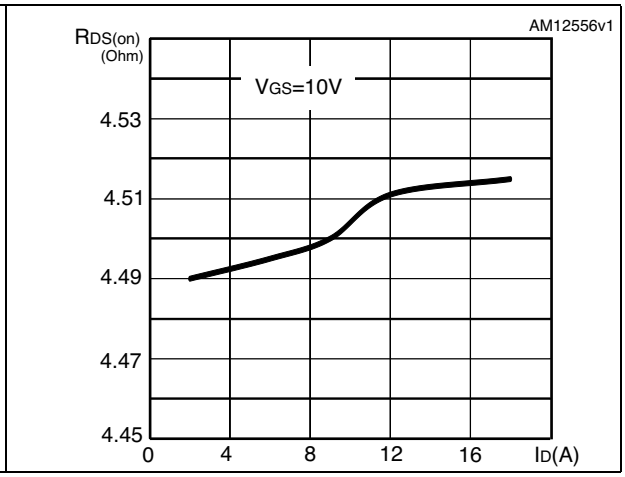


Figure 8. Capacitance variations

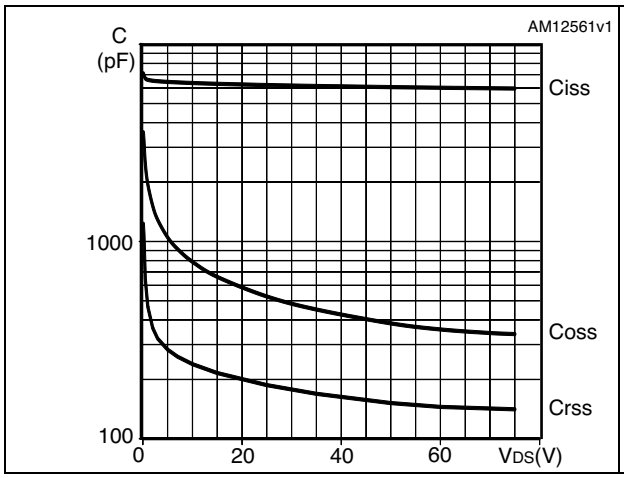


Figure 9. Normalized gate threshold voltage vs temperature

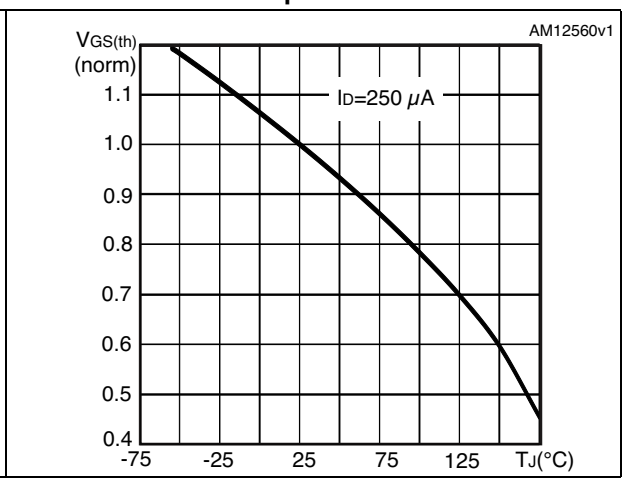


Figure 10. Normalized on-resistance vs temperature

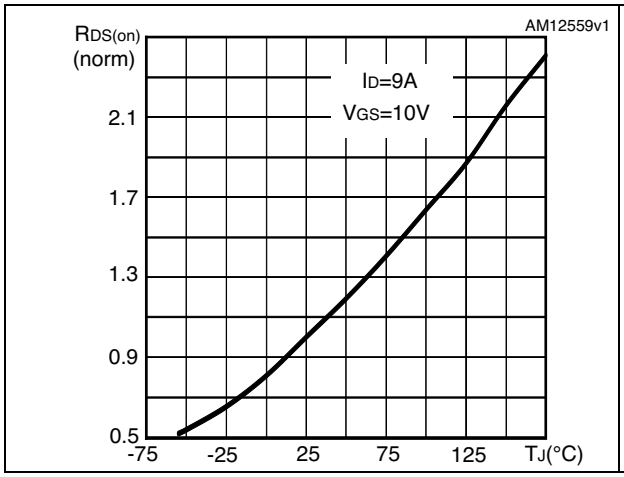


Figure 11. Source-drain diode forward characteristics

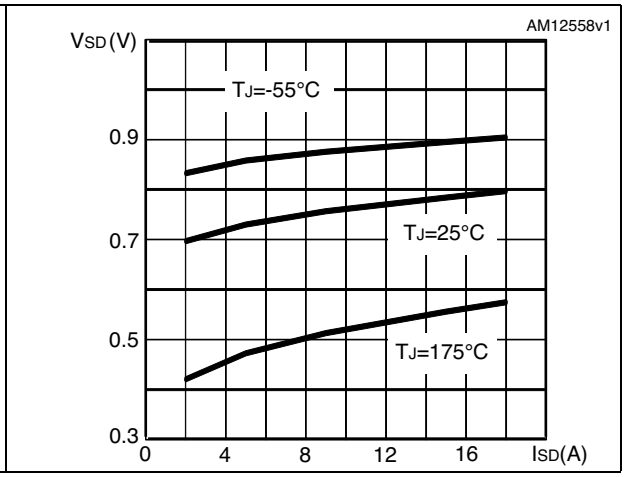
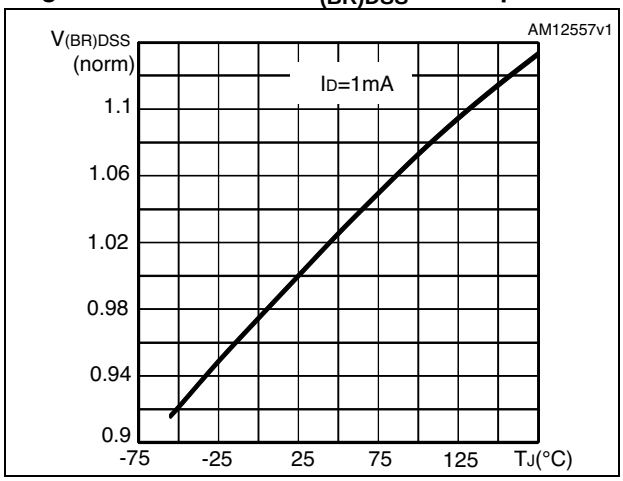


Figure 12. Normalized $V_{(BR)DSS}$ vs temperature



3 Test circuits

Figure 13. Switching times test circuit for resistive load

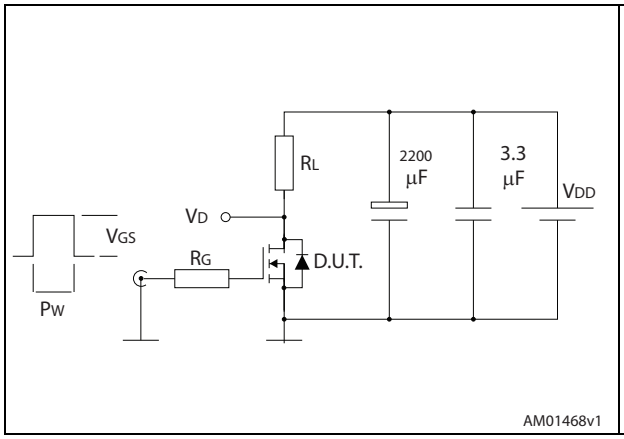


Figure 14. Gate charge test circuit

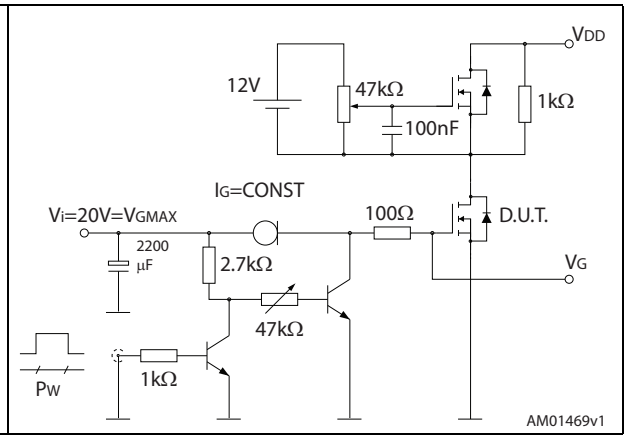


Figure 15. Test circuit for inductive load switching and diode recovery times

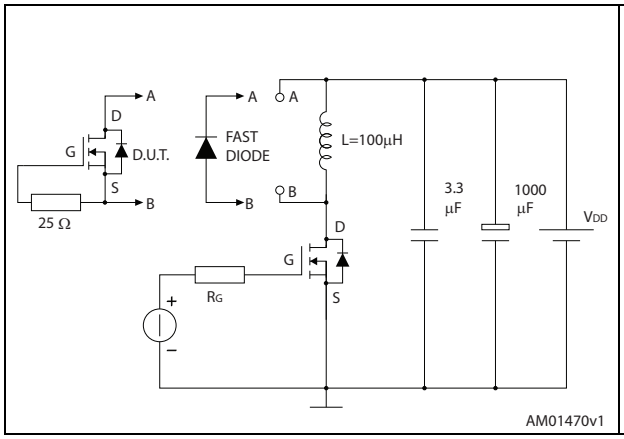


Figure 16. Unclamped inductive load test circuit

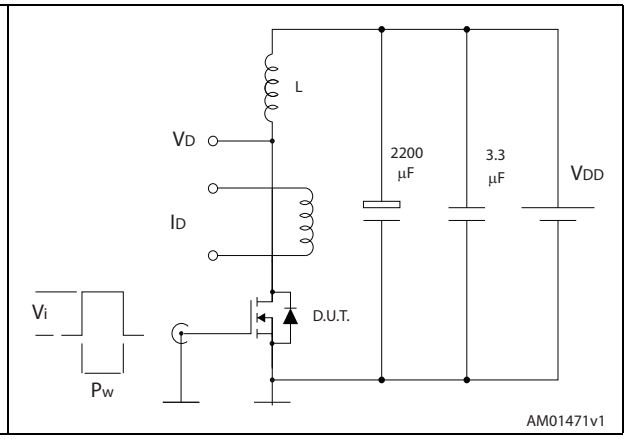


Figure 17. Unclamped inductive waveform

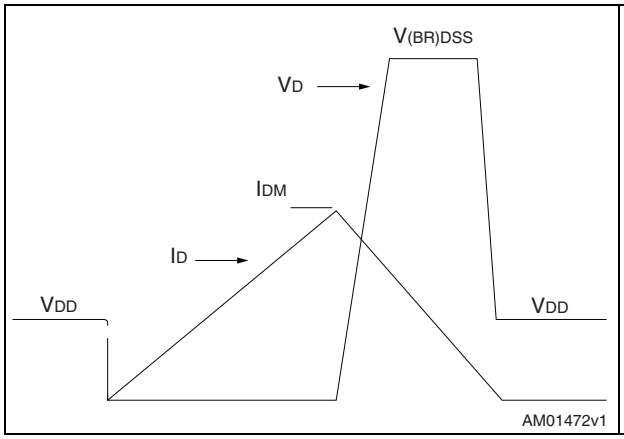
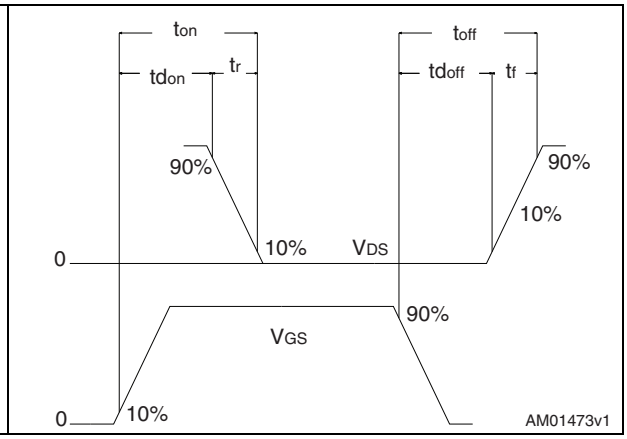


Figure 18. Switching time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*.
ECOPACK® is an ST trademark.

Figure 19. PowerFLAT™ 5x6 type S-C mechanical data

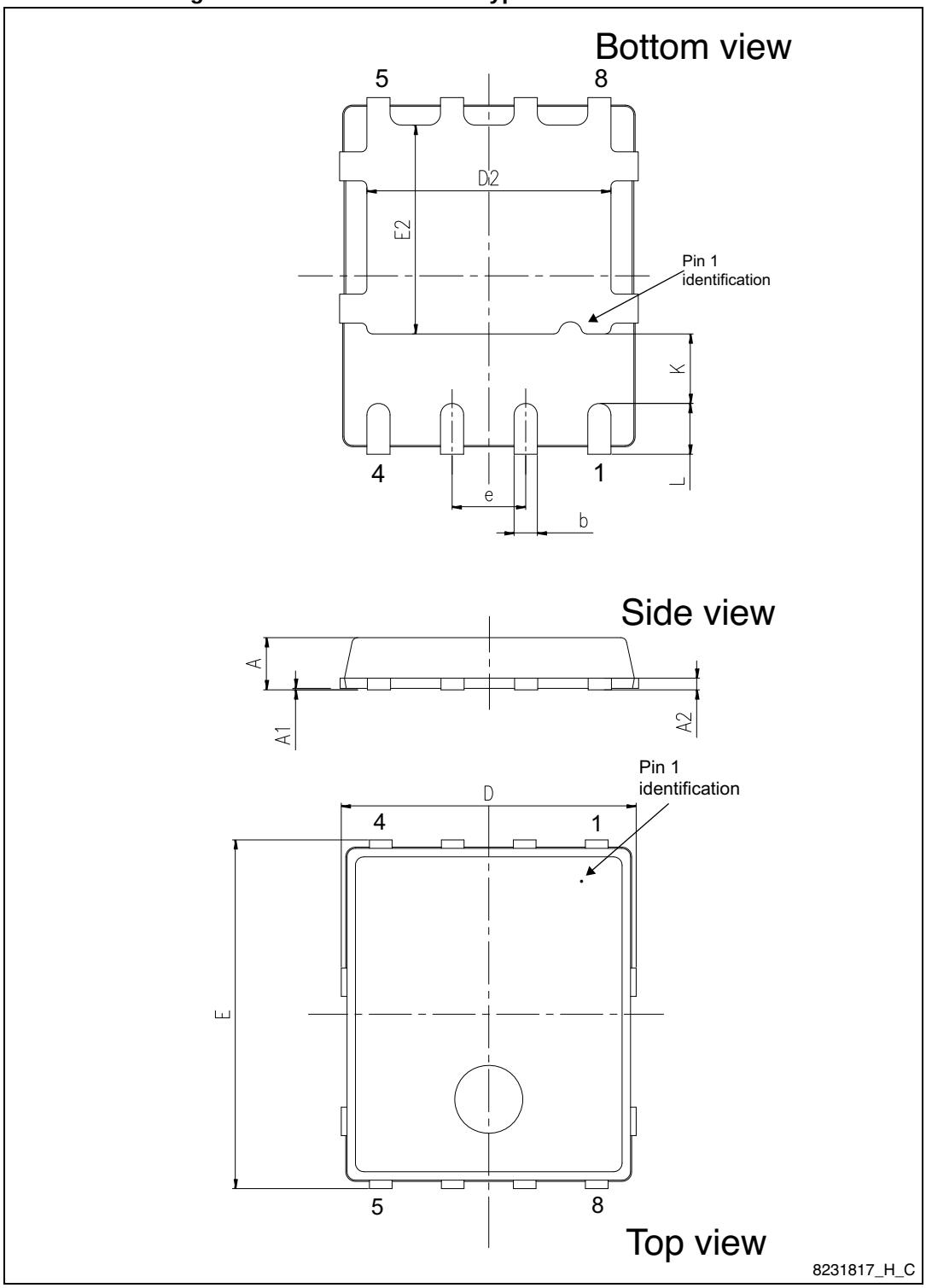
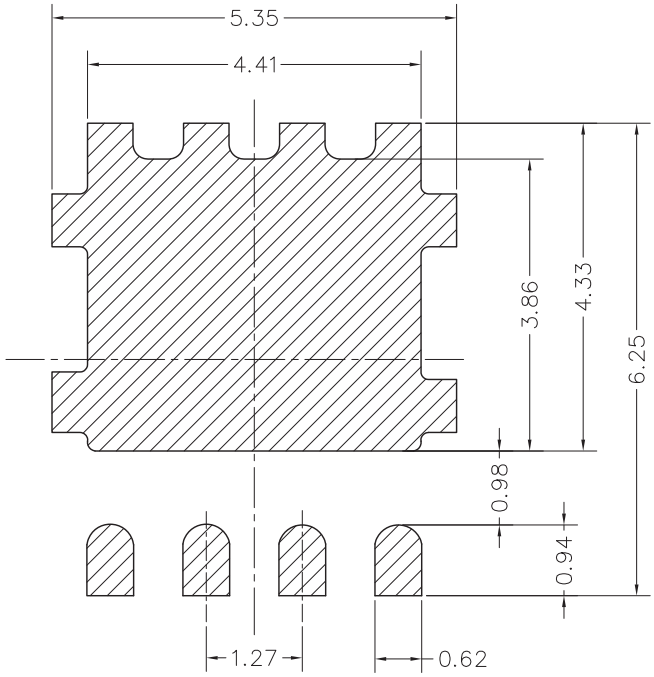


Table 9. PowerFLAT™ 5x6 type S-C mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
D		5.20	
E		6.15	
D2	4.11		4.31
E2	3.50		3.70
e		1.27	
e1		0.65	
L	0.715		1.015
K	1.05		1.35

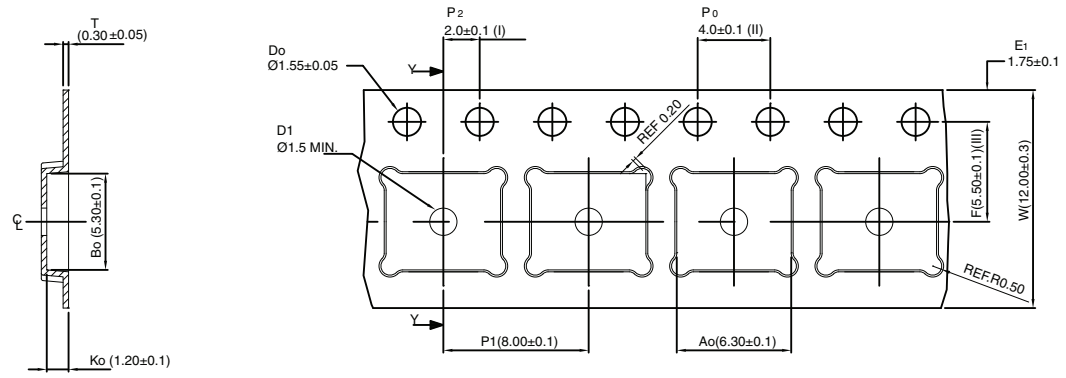
Figure 20. PowerFLAT™ 5x6 recommended footprint (dimensions in mm)



Footprint

5 Packaging mechanical data

Figure 21. PowerFLAT™ 5x6 tape[(a)]



(I) Measured from centerline of sprocket hole to centerline of pocket.

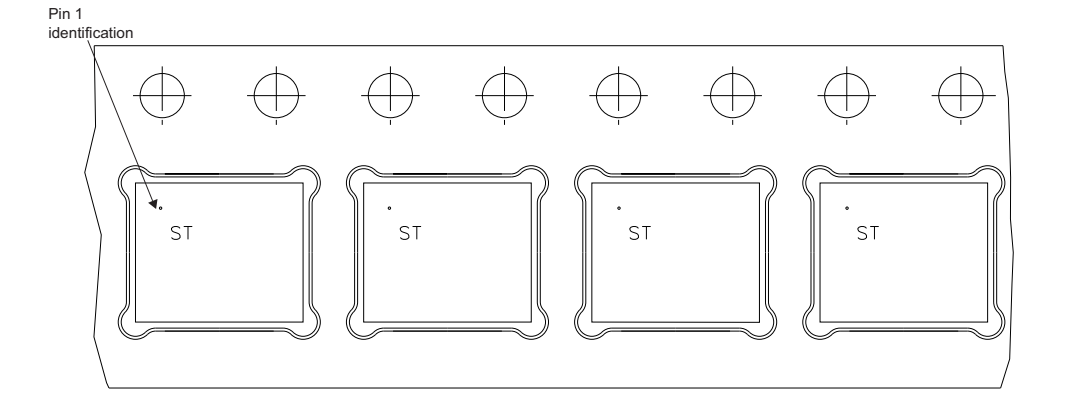
(II) Cumulative tolerance of 10 sprocket holes is ± 0.20 .

(III) Measured from centerline of sprocket hole to centerline of pocket.

Base and bulk quantity 3000 pcs

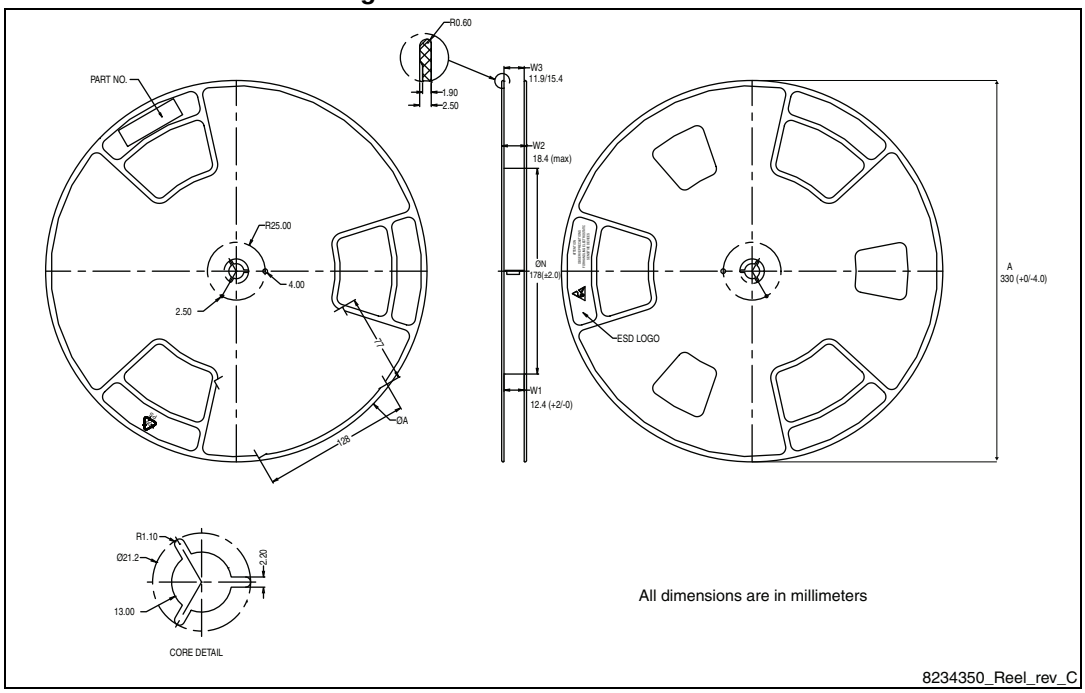
8234350_Tape_rev_C

Figure 22. PowerFLAT™ 5x6 package orientation in carrier tape.



a. All dimensions are in millimeters.

Figure 23. PowerFLAT™ 5x6 reel



6 Revision history

Table 10. Document revision history

Date	Revision	Changes
27-Apr-2011	1	First release.
10-Nov-2011	2	*Section 4: Package mechanical data* has been updated. Minor text changes.
11-Mar-2014	3	– Modified: *Table 2* (I_{DM} value), *Table 4* (I_{AS}, E_{AS} values) *Table 5* ($R_{DS(on)}$ typ. and max values), *Table 6* (typ. and test conditions), *Table 7* (test conditions and typ. values) *Table 8* (test conditions, typ. and max values) – Added: *Section 2.1: Electrical characteristics (curves)*. – Updated: *Section 4: Package mechanical data* – Minor text changes

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